

S1	0	257/685,686,690,692,723,724,737, 738,779,777,782,787	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/21 10:13
S2	14499	(257/685,686,690,692,723,724,737, 738,779,777,782,787).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/21 10:13
S3	6781	(438/109,107,110,613,612,112,124, 127).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/21 10:17
S4	539	(257/685).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/21 10:33
S5	2106	(257/723).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/21 10:34
S6	32	(US-20040256708-\$ or US-20040212064-\$ or US-20040207077-\$ or US-20040188818-\$ or US-20030092205-\$ or US-20020167079-\$ or US-20020000650-\$ or US-20040195682-\$ or US-20040195681-\$ or US-20040183190-\$ or US-20040159939-\$ or US-20040113260-\$ or US-20040090756-\$ or US-20030222342-\$ or US-20020047196-\$).did. or (US-6798054-\$ or US-6717251-\$ or US-6707143-\$ or US-5844315-\$ or US-5825082-\$ or US-5202578-\$ or US-5083189-\$ or US-6841870-\$ or US-6838776-\$ or US-6828665-\$ or US-6680532-\$ or US-6590281-\$ or US-6586845-\$ or US-6121676-\$ or US-5949133-\$ or US-5751555-\$ or US-5648683-\$).did.	US-PGPUB; USPAT	OR	ON	2005/03/21 11:09

S7	2	("6265763"   "6507098").PN. OR ("6841870").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/21 11:21
S8	5383	(multi-chip adj module or mcm) and interconnect\$4	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/22 14:30
S9	1278	(multi-chip adj module or mcm) and interconnect\$4 near2 substrate	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/21 11:26
S10	746	(multi-chip adj module or mcm) and interconnect\$4 near2 substrate and (bump or ball) and wire	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/21 13:18
S11	21	"WANG SUNG-FEI".in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/21 12:55
S12	1740	(257/692).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/21 13:24
S13	1489	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/21 13:24

S14	82	(US-20040256708-\$ or US-20040212064-\$ or US-20040207077-\$ or US-20040188818-\$ or US-20030092205-\$ or US-20020167079-\$ or US-20020000650-\$ or US-20040195682-\$ or US-20040195681-\$ or US-20040183190-\$ or US-20040159939-\$ or US-20040113260-\$ or US-20040090756-\$ or US-20030222342-\$ or US-20020047196-\$ or US-20040157361-\$ or US-20020158318-\$ or US-20020076910-\$ or US-20040212065-\$ or US-20050051904-\$ or US-20050006784-\$ or US-20040075171-\$ or US-20030164550-\$ or US-20030034563-\$ or US-20030006496-\$ or US-20020149097-\$).did. or (US-6798054-\$ or US-6717251-\$ or US-6707143-\$ or US-5844315-\$ or US-5825082-\$ or US-5202578-\$ or US-5083189-\$ or US-6841870-\$ or US-6838776-\$ or US-6828665-\$ or US-6680532-\$ or US-6590281-\$ or US-6586845-\$ or US-6121676-\$ or US-5949133-\$ or US-5751555-\$ or US-5648683-\$ or US-6265763-\$ or US-6864122-\$ or US-6864116-\$ or US-6521994-\$ or US-6404062-\$ or US-6323096-\$ or US-6297551-\$ or US-6236109-\$ or US-6043109-\$). did. or (US-6858938-\$ or US-6856027-\$ or US-6838754-\$ or US-6825567-\$ or US-6791192-\$ or US-6693362-\$ or US-6690089-\$ or US-6677669-\$ or US-6661091-\$ or US-6642610-\$ or US-6600221-\$ or US-6576997-\$ or US-6541871-\$ or US-6507098-\$ or US-6476474-\$ or US-6469395-\$ or US-6452278-\$ or US-6426559-\$ or US-6407456-\$ or US-6396116-\$ or US-6365963-\$ or US-6239367-\$ or US-6239366-\$ or US-6229215-\$ or US-6121682-\$ or US-5591959-\$ or US-5495398-\$). did. or (US-4555720-\$).did. or (US-20020081755-\$ or EP-1089336-\$).did.	US-PGPUB; USPAT; DERWENT	OR	ON	2005/03/22 09:02
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S15	15	("20030065880"   "20030218171"   "20040001380"   "20040024960"   "4062001"   "4074239"   "4876668"   "5146300"   "5311462"   "6121646"   "6208545"   "6229227"   "6342710"   "6373447"   "6551857").PN. OR ("6864122").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/21 15:14
S16	12	("5903052"   "6104089"   "6184580").PN. OR ("6507098").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/21 15:15
S17	2	("6265763"   "6507098").PN. OR ("6841870").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/21 15:42
S18	0	"219609".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/21 15:52
S19	2835	"misumi".in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/21 15:53
S20	15	"misumi kazuyuki".in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 09:12
S21	2	"6841870".pn.	US-PGPUB; USPAT; DERWENT	OR	ON	2005/03/22 09:03
S22	1111	(438/107).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/22 09:12
S23	0	(solder adj (bump or ball)) and gold and plastic and epoxy and "lead-free"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 10:48
S24	93	(solder adj (bump or ball)) and gold and plastic and epoxy and "lead-free"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 10:53

S25	49	(solder adj (bump or ball)) and gold near2 bump and epoxy near2 bump	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 11:07
S26	350	"quad flat non-leaded"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 11:09
S27	19	"quad flat non-leaded" and organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 14:25
S28	14521	(257/685,686,690,692,723,724,737,738,779,777,782,787).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/22 14:27
S29	6797	(438/109,107,110,613,612,112,124,127).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/22 14:27
S30	1	S28 and S29 and mcm and "multi-chip" and organic and "die pad"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/22 14:27
S31	359	(multi-chip adj module or mcm) and "chip pad"	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/22 15:57
S32	2468	substrate and passive and capacitor and embedded	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/22 14:55
S33	598	substrate and passive adj component and capacitor and embedded	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/22 15:45
S34	2	encapsul\$5 and "lead-free bump"	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/22 15:57
S35	12238	(multi-chip adj module or mcm) "lead-free bump"	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/22 15:58

S36	3	(multi-chip adj module or mcm) and "lead-free bump"	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/22 15:58
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L1	112	(US-20020000650-\$ or US-20020027294-\$ or US-20020028284-\$ or US-20020033378-\$ or US-20020047196-\$ or US-20020060357-\$ or US-20020063315-\$ or US-20020076910-\$ or US-20020079592-\$ or US-20020084518-\$ or US-20020088634-\$ or US-20020149097-\$ or US-20020153596-\$ or US-20020158318-\$ or US-20020167079-\$ or US-20020171157-\$ or US-20020190354-\$ or US-20030006492-\$ or US-20030006496-\$ or US-20030020068-\$ or US-20030034563-\$ or US-20030089923-\$ or US-20030092205-\$ or US-20030164550-\$ or US-20030222342-\$ or US-20040016999-\$).did. or (US-20040075171-\$ or US-20040090756-\$ or US-20040113260-\$ or US-20040157361-\$ or US-20040159939-\$ or US-20040183190-\$ or US-20040188818-\$ or US-20040195681-\$ or US-20040195682-\$ or US-20040207077-\$ or US-20040212064-\$ or US-20040212065-\$ or US-20040256708-\$ or US-20050006784-\$ or US-20050051904-\$).did. or (US-4555720-\$ or US-5083189-\$ or US-5202578-\$ or US-5495398-\$ or US-5591959-\$ or US-5648683-\$ or US-5751555-\$ or US-5825082-\$ or US-5844315-\$ or US-5949133-\$ or US-5949654-\$ or US-6043109-\$ or US-6097087-\$ or US-6121676-\$ or US-6121682-\$ or US-6229215-\$ or US-6236109-\$ or US-6239366-\$ or US-6239367-\$ or US-6265763-\$ or US-6276913-\$ or US-6297551-\$ or US-6317023-\$ or US-6321443-\$ or US-6323096-\$ or US-6365963-\$). did. or (US-6396116-\$ or US-6404062-\$ or US-6407456-\$ or US-6420779-\$ or US-6426559-\$ or US-6452278-\$ or US-6455355-\$ or US-6469335-\$ or US-6476469-\$ or US-6476474-\$ or US-6507098-\$ or US-6507170-\$ or US-6521994-\$ or	US-PGPUB; USPAT; DERWENT	OR	ON	2005/03/23 09:03
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